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**LM49101** March 23, 2009<br>**Boomer**<sup>®</sup> Audio Power Amplifier Series

### **Mono Class AB Audio Subsystem with a True Ground Headphone Amplifier and Earpiece Switch**

### **General Description**

*National*<br>Semiconductor

The LM49101 is a fully integrated audio subsystem with a mono power amplifier capable of delivering 540mW of continuous average power into an  $8\Omega$  BTL speaker load with 1% THD+N using a 3.3V supply. The LM49101 includes a separate stereo headphone amplifier that can deliver 44mW per channel into 32Ω loads using a 2.75V supply.

The LM49101 has four input channels. A pair of single-ended inputs and a fully differential input channel with volume control and amplification stages. Additionally, a bypass differential input is available that connects directly to the mono speaker outputs through an analog switch without any amplification or volume control stages. The LM49101 features a 32–step digital volume control on the input stage and an 8–step digital volume control on the headphone output stage.

The digital volume control and output modes, programmed through a two-wire I2C compatible interface, allows flexibility in routing and mixing audio channels.

The LM49101 is designed for cellular phones, PDAs, and other portable handheld applications. The high level of integration minimizes external components. The True Ground headphone amplifier eliminates the physically large DC blocking output capacitors reducing required board space and reducing cost.

### **Key Specifications**



■ Supply Voltage (V<sub>DD</sub>HP)  $1.8V \leq V_{DD}HP \leq 2.9V$ 

 $1.7V \leq 12CV<sub>DD</sub> \leq 5.5V$ 

- I<sup>2</sup>C Supply Voltage
- Output power

 $V_{DD}LS = 5V$ ,  $V_{DD}HP = 2.75V$  1% THD+N  $R_{L}$  = 8 $\Omega$  speaker 1.3W (typ)  $R_{L}$  = 32 $\Omega$  headphone 45mW (typ) ■ Output Power



- $R_L$  = 32 $\Omega$  headphone 40mW (typ)
- PSRR:
- $V_{DD} = 3.3V$ , 217Hz ripple, Mono In 90dB (typ)
- Shutdown power supply current 0.01μA (typ)

### **Features**

- Differential mono input and stereo single-ended input
- Separate earpiece (receiver) differential input
- Analog switch for a separate earpiece path
- 32-step digital volume control (-80 to +18dB)
- Three independent volume channels (Left, Right, Mono)
- Separate headphone volume control
- Flexible output for speaker and headphone output
- True Ground headphone amplifier eliminates large DC blocking capacitors reducing PCB space and cost.
- Hardware reset function
- RF immunity topology
- "Click and Pop" suppression circuitry
- Thermal shutdown protection
- Micro-power shutdown
- <sup>2</sup>C control interface
- Available in space-saving microSMD package

### **Applications**

- Portable electronic devices
- Mobile Phones
- PDAs



**FIGURE 1. Typical Audio Application Circuit**

**LO16tM7 LM49101**

### **Connection Diagrams**

#### **25 Bump micro SMD Package** 5 **IBYPASS**  $I$  BIAS  $\mathbf{I}$  $\mathbf{I}$ LIN  $MIN+$  $MIN \mathbf{I}$  $IN+$ **HW**  $\overline{4}$  $\int$  V<sub>DD</sub>HP HPGND J  $\mathbf{I}$ **RIN** ı  $I_{MONO-1}$ - 1 RESET 3  $\ensuremath{\mathsf{SCL}}$ **BUMPA1 HPR** Ł HPL  $\mathcal{L}$ GND ı  $\sqrt{1}$  GND  $\overline{2}$  $($ <sup>12</sup>CV<sub>DD</sub> $)$ I V<sub>SS</sub>CP 1 C<sub>1P</sub>  $\mathbf{I}$ **SDA**  $\sqrt{\frac{V_{DD}}{S}}$  $\mathbf{I}$  $\overline{\phantom{a}}$ 1  $IV_{DD}CP$ **IBYPASS**  $I$ CPGND I  $\overline{1}$  $C1N$  $M_{MONO}$  $\overline{\phantom{a}}$ V V  $\frac{1}{2}$  $\mathsf C$  $\overline{A}$ B D E 30086202

**Top View (Bump Side Down) Order Number LM49101TM, LM49101TMX See NS Package Number TMD25BCA**



**Top View XY - Date Code TT - Die Traceability G- Boomer Family L4 - LM49101TM**

30086204

### **Ordering Information**



## **Bump Descriptions**



### **Absolute Maximum Ratings (Notes [1,](#page-9-0) [2](#page-9-0))**

**If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.**



See AN-1112 "Micro SMD Wafer Level Chip Scale Package" Thermal Resistance

 $\theta_{JA}$  (Note 8) 51°C/W

### **Operating Ratings**



### **Electrical Characteristics**  $V_{DD}LS = 3.3V$ **,**  $V_{DD}HP = 2.75V$  $V_{DD}HP = 2.75V$  $V_{DD}HP = 2.75V$  **(Notes [1,](#page-9-0) 2)**

The following specifications apply for V<sub>DD</sub>LS = 3.3V, V<sub>DD</sub>HP = 2.75V, T<sub>A</sub> = 25°C, all volume controls set to 0dB, unless otherwise specified. LS = Loudspeaker, HP = Headphone, EP = Earpiece.





### **Electrical Characteristics**  $V_{DD}LS = 5.0V$ **,**  $V_{DD}HP = 2.75V$  **(Notes [1, 2\)](#page-9-0)**

The following specifications apply for V<sub>DD</sub>LS = 5.0V, V<sub>DD</sub>HP = 2.75V, T<sub>A</sub> = 25°C, all volume controls set to 0dB, unless otherwise specified. LS = Loudspeaker, HP = Headphone, EP = Earpiece. T



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### <span id="page-9-0"></span>**I <sup>2</sup>C Interface 2.2V** ≤ **I2C\_VDD** <sup>≤</sup> **5.5V,** (Notes 1, 2)

The following specifications apply for V<sub>DD</sub>LS = 5.0V and 3.3V, 2.2V ≤ I<sup>2</sup>C\_V<sub>DD</sub> ≤ 5.5V, T<sub>A</sub> = 25°C, unless otherwise specified.



### **I <sup>2</sup>C Interface 1.7V** ≤ **I2C\_VDD** <sup>≤</sup> **2.2V,** (Notes 1, 2)

The following specifications apply for V<sub>DD</sub>LS = 5.0V and 3.3V, T<sub>A</sub> = 25°C, 1.7V ≤ I<sup>2</sup>C\_V<sub>DD</sub> ≤ 2.2V, unless otherwise specified.



**Note 1:** "Absolute Maximum Ratings" indicate limits beyond which damage to the device may occur, including inoperability and degradation of device reliability and/or performance. Functional operation of the device and/or non-degradation at the Absolute Maximum Ratings or other conditions beyond those indicated in the Recommended Operating Conditions is not implied. The Recommended Operating Conditions indicate conditions at which the device is functional and the device should not be operated beyond such conditions. All voltages are measured with respect to the ground pin, unless otherwise specified

**Note 2:** The Electrical Characteristics tables list guaranteed specifications under the listed Recommended Operating Conditions except as otherwise modified or specified by the Electrical Characteristics Conditions and/or Notes. Typical specifications are estimations only and are not guaranteed.

 $\sf Note\ 3:$  The maximum power dissipation must be derated at elevated temperatures and is dictated by  $T_{\sf JMAX}$ ,  $\theta_{\sf JA}$ , and the ambient temperature,  $T_{\sf A}.$  The maximum allowable power dissipation is  ${\sf P}_{\sf DMAX}$  =  $({\sf T}_{\sf JMAX}$  -  ${\sf T_A})$  /  $\theta_{\sf JA}$  or the number given in Absolute Maximum Ratings, whichever

**Note 4:** Human body model, applicable std. JESD22-A114C.

**Note 5:** Machine model, applicable std. JESD22-A115-A.

**Note 6:** Typical values represent most likely parametric norms at T<sub>A</sub> = +25°C, and at the Recommended Operation Conditions at the time of product characterization and are not guaranteed.

**Note 7:** Datasheet min/max specification limits are guaranteed by test or statistical analysis.

**Note 8:** The given  $θ_{JA}$  is for an LM49101 mounted on a demonstration board.

**Note 9:** Refer to the I2C timing diagram, Figure 2.

### **Typical Performance Characteristics**





**THD+N vs Frequency VDDLS = 3.3V, VDDHP = 1.8V, R<sup>L</sup>** = 32Ω **SE, P<sup>O</sup> = 5mW/Ch, Mode 8 (Left/Right ), 80kHz BW**



**THD+N vs Frequency VDDLS = 3.3V, VDDHP = 1.8V, R<sup>L</sup>** = 8Ω **BTL, R<sup>L</sup>** = 32Ω **SE, P<sup>O</sup> = 250mW BTL, P<sup>O</sup> = 5mW/Ch SE, Mode 10 (L/R) LS (EP Mode) = 0, 80kHz BW**









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**THD+N vs Frequency VDDLS = 5V, VDDHP = 2.75V, R<sup>L</sup>** = 32Ω **SE, P<sup>O</sup> = 20mW/Ch, Mode 8 (Left/Right), 80kHz BW**







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 $0.05$  $0.02$  $0.01$ ≢ 0.005 0.002 0.001  $20<sub>m</sub>$  $\overline{60}$ m  $2m$  $10<sub>m</sub>$  $1<sub>m</sub>$  $5<sub>m</sub>$ **OUTPUT POWER (W)** 30086246

**THD+N vs Output Power**  $V_{DD}LS = 3.3V$ ,  $V_{DD}HP = 1.8V$  & 2.75V,  $f = 1$ kHz, **RL** = 32Ω **SE, Mode 10 (Left/Right), 80kHz BW**





























![](_page_15_Figure_1.jpeg)

![](_page_15_Figure_2.jpeg)

![](_page_15_Figure_3.jpeg)

![](_page_15_Figure_4.jpeg)

![](_page_15_Figure_5.jpeg)

**Supply Current vs Supply Voltage (V<sub>DD</sub>LS)**  $V_{DD}HP = 2.75V$ , No Load, Gain\_SD = 0 & 1 **LS (EP\_Mode) = 0 & 1, Mode 2**

![](_page_15_Figure_7.jpeg)

**Supply Current vs Supply Voltage (V<sub>DD</sub>LS)**  $V_{DD}$ HP = 2.75V, No Load, Gain\_SD = 0 or 1 **LS (EP\_Mode) = 0 & 1, Mode 15**

![](_page_15_Figure_9.jpeg)

**Output Power vs Supply Voltage (V<sub>DD</sub>HP) VDDLS = 3.3V, R<sup>L</sup>** = 32Ω **SE,**

![](_page_15_Figure_11.jpeg)

### **Application Information**

#### **I 2C COMPATIBLE INTERFACE**

The LM49101 is controlled through an I2C compatible serial interface that consists of a serial data line (SDA) and a serial clock (SCL). The clock line is uni-directional. The data line is bi-directional (open drain). The LM49101 and the master can communicate at clock rates up to 400kHz. Figure 2 shows the I 2C interface timing diagram. Data on the SDA line must be stable during the HIGH period of SCL. The LM49101 is a transmit/receive slave-only device, reliant upon the master to generate the SCL signal. Each transmission sequence is framed by a START condition and a STOP condition (Figure 3). Each data word, device address and data, transmitted over the bus is 8 bits long and is always followed by an acknowledge pulse (Figure 4). The LM49101 device address is 11111000.

#### I<sup>2</sup>C INTERFACE POWER SUPPLY PIN (I<sup>2</sup>CV<sub>DD</sub>)

The LM49101's I2C interface is powered up through the I<sup>2</sup>CV<sub>DD</sub> pin. The LM49101's I<sup>2</sup>C interface operates at a voltage level set by the  $12CV<sub>DD</sub>$  pin which can be set independent to that of the main power supply pin  $V_{DD}LS$ . This is ideal whenever logic levels for the I<sup>2</sup>C interface are dictated by a microcontroller or microprocessor that is operating at a lower supply voltage than the  $V_{DD}$ LS voltage.

#### **I 2C BUS FORMAT**

The I2C bus format is shown in Figure 4. The START signal, the transition of SDA from HIGH to LOW while SCL is HIGH, is generated, alerting all devices on the bus that a device address is being written to the bus.

The 7-bit device address is written to the bus, most significant bit (MSB) first, followed by the R/W bit. R/W = 0 indicates the master is writing to the slave device,  $R/\overline{W} = 1$  indicates the master wants to read data from the slave device. Set  $R/\overline{W}$  = 0; the LM49101 is a WRITE-ONLY device and will not respond to the R/ $\overline{W}$  = 1. The data is latched in on the rising edge of the clock. Each address bit must be stable while SCL is HIGH. After the last address bit is transmitted, the master device releases SDA, during which time, an acknowledge clock pulse is generated by the slave device. If the LM49101 receives the correct address, the device pulls the SDA line low, generating an acknowledge bit (ACK).

Once the master device registers the ACK bit, the 8-bit register data word is sent. Each data bit should be stable while SCL is HIGH. After the 8-bit register data word is sent, the LM49101 sends another ACK bit. Following the acknowledgement of the register data word, the master issues a STOP bit, allowing SDA to go high while SCL is high.

![](_page_16_Figure_10.jpeg)

<u>nnnnnnn nnnnnnnn n</u> SCL

**ACK** 

**SDA** STAR<sup>-</sup>

**MSB** 

 $R/\sqrt{W}$ **DEVICE ADDRESS** LSB

**MSB REGISTER DATA** 

**STOP** 300862s2

LSB

ACK

**FIGURE 4. Start and Stop Diagram**

**TABLE 1. Chip Address**

![](_page_17_Picture_312.jpeg)

**TABLE 2. Control Registers**

![](_page_17_Picture_313.jpeg)

**Notes:** All registers default to 0 on initial power-up.

1. GAMP\_SD: Is used to shut down gain amplifiers not in use and reduce current consumption. See Table 3.

2. LS (EP\_Mode): Loudspeaker power amplifier bias current reduction. See Table 3.

3. Turn\_On\_Time: Reduces the turn on time for faster activation. See Table 3.

4. Power\_On: Master Power on bit. See Table 3.

5. EP Bypass: Earpiece bypass mode to allow BYPASS inputs to drive speaker outputs. See Table 4

6. HPR\_SD: Will shutdown one channel of the headphone amplifier. See Table 4.

7. Mode\_Control: Sets the output mode. See Table 4.

8. Input Mute: Controls muting of the inputs except the BY-PASS inputs. See Table 5.

9. LS Gain: Sets the gain of the loudspeaker amplifier to 0dB or 6dB. See Table 5.

10. HP\_Gain: Sets the headphone amplifier output gain. See Table 5.

11. Mono\_Vol/Left\_Vol/Right\_Vol: Sets the input volume for Mono, Left and Right inputs. See Table 6.

#### **TABLE 3. General Control Register**

![](_page_18_Picture_131.jpeg)

![](_page_19_Picture_561.jpeg)

### **TABLE 4. Output Mode Control Register (see key below table)**

M : MIN, Mono differential input

L : LIN, Left single-ended input

R : RIN, Right single-ended input

SD : Shutdown

 $\mathsf{G}_\mathsf{M}$  : Mono\_Vol setting determined by the Mono Input Volume Control register, See Table 6.

 ${\tt G}_{\sf L}$  : Left $\char`_\hspace{0.15mm}$  Vol setting determined by the Left Input Volume Control register, See Table 6.

 $\mathsf{G}_{\mathsf{R}}$  : Right\_Vol setting determined by the Right Input Volume Control register, See Table 6.

![](_page_20_Picture_134.jpeg)

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![](_page_21_Picture_267.jpeg)

#### **TABLE 6. Input Volume Control Registers**

#### **HW RESET FUNCTION**

The LM49101 can be globally reset without using the I2C controls. When the HW RESET pin is set to a logic low the LM49101 will enter into shutdown, the mode control bits of the Output Mode Control register, volume control registers and Power\_On bits will be set to the default value of zero. The other bits will retain their values. The LM49101 cannot be activated until the HW RESET pin is set to a logic high voltage. When the HW RESET is set to a logic high then the I2C controls can activate and set the register control bits.

#### **GAMP\_SD BIT**

The GAMP\_SD bit allows for reduced power consumption. When set to '1' the gain amplifiers on unused inputs will be shutdown saving approximately 0.4mA per input in shutdown. For example, in Mode 1 only the mono inputs are in use. Setting GAMP\_SD to '1' will shut down the gain amplifiers for the left and right inputs reducing current draw from the  $V_{DD}LS$ supply by approximately 0.8mA. The GAMP\_SD bit does not need to be set each time when changing modes as the LM49101 will automatically activate and deactivate the needed inputs based on the mode selected.

When operating with GAMP\_SD set to '1', a transient may be observed on the outputs when changing modes. During power up, the LM49101 uses a start up sequence to eliminate any pops and clicks on the outputs. The volume control circuitry is powered up first followed by the other internal circuitry with the output amplifiers being powered up last. If a mode change requires a gain amplifier to turn on then a potential transient may be created that is amplified on the already active outputs. To eliminate unwanted noise on the outputs the Power\_On bit should be used to turn off the LM49101 before changing modes, perform a mode change, then turn the LM49101 back on. This procedure will cause the LM49101 to follow the start up sequence.

#### **LS (EP\_MODE) BIT**

The LS (EP\_Mode) bit selects the amount of bias current in the loudspeaker amplifier. Setting the LS (EP\_Mode) bit to a '1' will reduce the amount of current from the  $V_{DD}LS$  supply by approximately 0.5mA. The THD performance of the loudspeaker amplifier will be reduced as a result of lower bias current. See the performance graphs in the Typical Performance Characteristics section above.

#### **TURN\_ON\_TIME BIT**

The Turn\_On\_Time bit determines the delay time from the Power On bit set to '1' and the internal circuits ready. For input capacitor values up to 0.47μF the Turn\_On\_Time bit can be set to fast mode by setting the bit to a '1'. When the input capacitor values are larger than 0.47μF then the Turn\_On\_Time bit should be set to '0' for normal turn-on time and higher delay. This allows sufficient time to charge the input capacitors to the  $\frac{1}{2}$  V<sub>DD</sub>LS bias voltage.

#### **POWER\_ON BIT**

The Power\_On bit is the master control bit to activate or deactivate the LM49101. All registers can be loaded independent of the Power\_On bit setting as long as the IC is powered correctly. Cycling the Power\_On bit does not change the values of any registers nor return all bits to the default power on value of zero. The Power\_On bit only determines whether the IC is on or off.

#### **EP BYPASS BIT**

The EP Bypass bit is used to set the LM49101 to earpiece mode. When this bit is set the analog switch is activated and the rest of the IC blocks except for the I2C circuitry will go into shutdown for minimal current consumption.

#### **HPR\_SD BIT**

The HPR\_SD bit will deactivate the right headphone output amplifier. This bit is provided to reduce power consumption when only one headphone output is needed.

#### **MODE\_CONTROL BITS**

The LM49101 includes a comprehensive mixer multiplexer controlled through the I2C interface. The mixer/multiplexer allows any input combination to appear on any output of LM49101. Multiple input paths can be selected simultaneously. Under these conditions, the selected inputs are mixed together and output on the selected channel. Table 4 shows how the input signals are mixed together for each possible input selection.

#### **INPUT MUTE BIT**

The Input Mute bit will mute all inputs except the Bypass inputs when set to a '1'. This allows complete and quick mute of the Mono, Left, and Right inputs without changing the Volume Control registers or HP\_Gain bits. The volume and HP Gain bits retain their values when the Input Mute is enabled or disabled.

The Input Mute bit can be used to mute all the inputs when other chips in a system, such as the baseband IC, create transients causing unwanted noise on the outputs of the LM49101. This added feature eliminates the need for power cycling the LM49101.

#### **LS\_GAIN BIT**

The loudspeaker amplifier can have an additional gain of 0dB or 6dB by using the LS\_Gain bit. The Mono input has 6dB of attenuation before the volume control (see Figure 1) while the Left and Right inputs do not. The LS\_Gain bit is used to account for the different attenuation levels for each input and to achieve maximum output power. To obtain maximum output power on the loudspeaker outputs, the LS\_Gain bit should be se to '1' for Modes 1, 5, 9, 13.

#### **HP\_GAIN BITS**

The headphone outputs have an additional, single volume control set by the three HP\_Gain bits in the Output Gain Control register. The HP\_Gain volume setting controls the output level for both the left and the right headphone outputs.

#### **VOLUME CONTROL BITS**

The LM49101 has three independent 32-step volume controls, one for each of the inputs. The five bits of the Volume Control registers sets the volume for the specified input channel.

#### **SHUTDOWN FUNCTION**

The LM49101 features the following shutdown controls.

Bit D4 (GAMP\_SD) of the GENERAL CONTROL register controls the gain amplifiers. When GAMP\_SD = 1, it disables the gain amplifiers that are not in use. For example, in Modes 1, 4 and 5, the Mono inputs are in use, so the Left and Right input gain amplifiers are disabled, causing the  $I_{DD}$  to be minimized.

Bit D0 (Power\_On) of the GENERAL CONTROL register is the global shutdown control for the entire device. Set Power\_On = 0 for normal operation. Power\_On = 1 overrides any other shutdown control bit.

#### **DIFFERENTIAL AMPLIFIER EXPLANATION**

The LM49101 features a differential input stage, which offers improved noise rejection compared to a single-ended input amplifier. Because a differential input amplifier amplifies the difference between the two input signals, any component common to both signals is cancelled. An additional benefit of the differential input structure is the possible elimination of the DC input blocking capacitors. Since the DC component is common to both inputs, and thus cancelled by the amplifier, the LM49101 can be used without input coupling capacitors when configured with a differential input signal.

#### **BRIDGE CONFIGURATION EXPLAINED**

By driving the load differentially through the MONO outputs, an amplifier configuration commonly referred to as "bridged mode" is established. Bridged mode operation is different from the classical single-ended amplifier configuration where one side of the load is connected to ground.

A bridge amplifier design has a few distinct advantages over the single-ended configuration, as it provides differential drive to the load, thus doubling output swing for a specified supply voltage. Four times the output power is possible as compared to a single-ended amplifier under the same conditions. This increase in attainable output power assumes that the amplifier is not current limited or clipped.

A bridge configuration, such as the one used in LM49101, also creates a second advantage over single-ended amplifiers. Since the differential outputs are biased at half-supply, no net DC voltage exists across the load. This eliminates the need for an output coupling capacitor which is required in a single supply, single-ended amplifier configuration. Without an output coupling capacitor, the half-supply bias across the load would result in both increased internal IC power dissipation and also possible loudspeaker damage.

#### **POWER DISSIPATION**

Power dissipation is a major concern when designing a successful amplifier, whether the amplifier is bridged or singleended. A direct consequence of the increased power delivered to the load by a bridge amplifier is an increase in internal power dissipation. The power dissipation of the LM49101 varies with the mode selected. The maximum power dissipation occurs in modes where all inputs and outputs are active (Modes 6, 7, 8, 9, 10, 11, 13, 14, 15). The power dissipation is dominated by the Class AB amplifier. The maximum power dissipation for a given application can be derived from the power dissipation graphs or from Equation 1.

$$
P_{DMAX} = 4^{*}(V_{DD})^{2}/(2\pi^{2}R_{L})
$$
 (1)

It is critical that the maximum junction temperature  $(T_{JMAX})$  of 150 $^{\circ}$ C is not exceeded.  $T_{JMAX}$  can be determined from the power derating curves by using  $P_{DMAX}$  and the PC board foil area. By adding additional copper foil, the thermal resistance of the application can be reduced from the free air value, resulting in higher P<sub>DMAX</sub>. Additional copper foil can be added to any of the leads connected to the LM49101. It is especially effective when connected to  $V_{DD}$ , GND, and the output pins. Refer to the application information on the LM49101 reference design board for an example of good heat sinking. If  $T_{JMAX}$  still exceeds 150°C, then additional changes must be made. These changes can include reduced supply voltage, higher load impedance, or reduced ambient temperature. Internal power dissipation is a function of output power. Refer to the **Typical Performance Characteristics** curves for

power dissipation information for different output powers and output loading.

#### **POWER SUPPLY BYPASSING**

As with any amplifier, proper supply bypassing is critical for low noise performance and high power supply rejection. The capacitor location on both the bypass and power supply pins should be as close to the device as possible. Typical applications employ a 5V regulator with 10µF tantalum or electrolytic capacitor and a ceramic bypass capacitor which aid in supply stability. This does not eliminate the need for bypassing the supply nodes of the LM49101. The selection of a bypass capacitor, especially C<sub>B</sub>, is dependent upon PSRR requirements, click and pop performance, system cost, and size constraints.

#### **GROUND REFERENCED HEADPHONE AMPLIFIER**

The LM49101 features a low noise inverting charge pump that generates an internal negative supply voltage. This allows the headphone outputs to be biased about GND instead of a nominal DC voltage, like traditional headphone amplifiers. Because there is no DC component, the large DC blocking capacitors (typically 220μF) are not necessary. The coupling capacitors are replaced by two small ceramic charge pump capacitors, saving board space and cost. Eliminating the output coupling capacitors also improves low frequency response. In traditional headphone amplifiers, the headphone impedance and the output capacitor from a high-pass filter that not only blocks the DC component of the output, but also attenuates low frequencies, impacting the bass response. Because the LM49101 does not require the output coupling capacitors, the low frequency response of the device is not degraded by external components. In addition to eliminating the output coupling capacitors, the ground referenced output nearly doubles the available dynamic range of the LM49101 headphone amplifiers when compared to a traditional headphone amplifier operating from the same supply voltage.

#### **HEADPHONE & CHARGE PUMP SUPPLY VOLTAGE (VDDHP & VDDCP)**

The headphone outputs are centered at ground by using dual supply voltages for the headphone amplifier. The positive power supply is set by the voltage on the  $V_{DD}HP$  pin while the negative supply is created with an internal charge pump. The negative supply voltage is equal in magnitude but opposite in voltage to the voltage on the  $V_{DD}CP$  pin.

#### **INPUT CAPACITOR SELECTION**

Input capacitors may be required for some applications, or when the audio source is single-ended. Input capacitors block the DC component of the audio signal, eliminating any conflict between the DC component of the audio source and the bias voltage of the LM49101. The input capacitors create a highpass filter with the input resistors  $R_{IN}$ . The -3dB point of the high-pass filter is found using Equation (2) below.

$$
f = 1 / 2\pi R_{IN} C_{IN} \quad (Hz)
$$
 (2)

Where the value of  $R_{IN}$  is given in the Electrical Characteristics Table as  $Z_{IN}$ .

When the LM49101 is using a single-ended source, power supply noise on the ground is seen as an input signal. Setting the high-pass filter point above the power supply noise frequencies, 217Hz in a GSM phone, for example, filters out the noise such that it is not amplified and heard on the output. Capacitors with a tolerance of 10% or better are recommended for impedance matching and improved CMRR and PSRR.

#### **CHARGE PUMP FLYING CAPACITOR (C<sup>1</sup> )**

The flying capacitor  $(C_1)$ , see Figure 1, affects the load regulation and output impedance of the charge pump. A  $C_1$  value that is too low results in a loss of current drive, leading to a loss of amplifier headroom. A higher valued  ${\mathsf C}_1$  improves load regulation and lowers charge pump output impedance to an extent. Above 2.2 $\mu$ F, the  $R_{DS(ON)}$  of the charge pump switches and the ESR of  $C_1$  and  $C_{s3}$  dominate the output impedance. A lower value capacitor can be used in systems with low maximum output power requirements.

#### **CHARGE PUMP HOLD CAPACITOR (CS3)**

The value and ESR of the hold capacitor  $C_{s3}$  directly affects the ripple on  $V_{SS}$ CP. Increasing the value of  $\widetilde{C}_{ss}$  reduces output ripple. Decreasing the ESR of  $C_{s3}$  reduces both output ripple and charge pump output impedance. A lower value capacitor can be used in systems with low maximum output power requirements.

#### **SELECTION OF INPUT RESISTORS**

The Bypass In inputs connect to the loudspeaker output through an FET switch when EP Bypass is active (see Figure 5). Because THD through this path is mainly dominated by the switch impedance variation, adding input resistors ( $\mathsf{R}_{\mathsf{3}}$  and  $\mathsf{R}_4$  in Figure 5) will help reduce impedance effects resulting in improved THD. For example, a change in the switch impedance from 2Ω to 3Ω is a 67% change in impedance. If  $10\Omega$  input resistors are used then the impedance change is from 12Ω to 13Ω, only 7.7% impedance variation. The analog switch impedance is typically 2Ω to 3.4Ω. The switch impedance change is a result of heating and the increase in  $R_{DS(ON)}$  of the FETs.

The value of the input resistors must be balanced against the amount of output current and the load impedance on the loudspeaker outputs. A higher value input resistor reduces the effects of switch impedance variation but also causes voltage drop and reduced power to the load on the loudspeaker outputs.

The current through the FET switch should not exceed 500mA or die heating may cause thermal shut down activation and potential IC damage.

#### **MINIMUM POWER OPERATION**

The LM49101 has several options to reduce power consumption and is designed to conserve power when possible. When a speaker only mode is selected the headphone sections are shutdown and the current drawn from the  $V_{DD}HP/V_{DD}CP$ power supply will be zero. When a headphone mode is selected the current drawn from the  $V_{DD}LS$  supply is also reduced by shutting down unused circuitry. See the various Supply Current vs Supply Voltage graphs in the Typical Performance Characteristics section.

To reduce power consumption further, the additional control bits GAMP\_SD, LS (EP Mode), and HPR\_SD are provided. When low power consumption is more important than the THD performance of the loudspeaker the LS (EP\_mode) bit should be set to '1' saving approximately 0.5mA from the V<sub>DD</sub>LS supply. The GAMP\_SD bit should be set on to save approximately 0.4mA for each input shut down. For modes where only the mono input is used, up to 0.8mA can be saved from the  $V_{DD}$ LS supply. Also, the HPR\_SD bit can be used to shut down the right headphone channel reducing power consumption when only one amplifier headphone output is needed.

Additionally, the supply voltages for the different  $V_{DD}$  pins ( $V_{DD}$ LS,  $V_{DD}$ HP, and  $V_{DD}$ CP) can be set to the minimum needed values to obtain the output power levels required by the design. By reducing the supply voltage the total power consumption will be reduced.

For best system efficiency, a DC-DC converter (buck) can be used to power the  $V_{DD}HP$  and  $V_{DD}CP$  voltages from the  $V<sub>DD</sub>LS$  supply instead of a linear regulator. DC-DC converters achieve much higher efficiency (> 90%) than even a low dropout regulator (LDO).

![](_page_25_Figure_0.jpeg)

**FIGURE 5. Demo Board Circuit**

### **Demonstration Board**

The demonstration board (see Figure 5) has connection and jumper options to be powered partially from the USB bus or from external power supplies. Additional options are to power the I<sup>2</sup>C logic and loudspeaker amplifier ( $V_{DD}LS$ ) from a single power supply or separate power supplies. The headphone amplifier and charge pump can also be powered from the same supply as long as the voltage limits for each power supply are not exceeded, although the option is not built into the board. See theOperating Ratings for each supply's range limit. When powered from the USB bus the  $I^2CV_{DD}$  will be set to 3.3V and the  $V_{DD}$ LS will be set to 5V. Jumper headers  $J_{13}$  and  $J_{12}$  must be set accordingly. If a single power supply for I<sup>2</sup>CV<sub>DD</sub> and V<sub>DD</sub>LS is desired then header J<sub>5</sub> should be used with a jumper added to header  $J_{11}$  to connect I<sup>2</sup>CV<sub>DD</sub> to the external supply voltage connected to  $J_5$  (see Figure 5). Connection headers  $J_1$  and  $J_2$  are provided along with the stereo headphone jack  $J_4$  for easily connection and monitoring of the headphone outputs.

**LM4910 LM49101**

### **LM49101 microSMD Demo Board Views**

![](_page_26_Picture_2.jpeg)

**Composite View**

![](_page_26_Figure_4.jpeg)

**Top Layer**

![](_page_26_Figure_6.jpeg)

![](_page_26_Figure_7.jpeg)

**Silk Screen**

![](_page_26_Picture_9.jpeg)

**Internal Layer 1**

![](_page_26_Figure_11.jpeg)

**Bottom Layer**

### **LM49101 Reference Demo Board Bill Of Materials**

![](_page_27_Picture_315.jpeg)

**TABLE 7. Bill Of Materials**

### **PCB Layout Guidelines**

This section provides practical guidelines for mixed signal PCB layout that involves various digital/analog power and ground traces. Designers should note that these are only "rule-of-thumb" recommendations and the actual results will depend heavily on the final layout.

### **General Mixed Signal Layout Recommendations**

#### **SINGLE-POINT POWER AND GROUND CONNECTIONS**

The analog power traces should be connected to the digital traces through a single point (link). A "Pi-filter" can be helpful in minimizing high frequency noise coupling between the analog and digital sections. It is further recommended to put digital and analog power traces over the corresponding digital and analog ground traces to minimize noise coupling.

### **PLACEMENT OF DIGITAL AND ANALOG COMPONENTS**

All digital components and high-speed digital signals traces should be located as far away as possible from analog components and circuit traces.

#### **AVOIDING TYPICAL DESIGN AND LAYOUT PROBLEMS**

Avoid ground loops or running digital and analog traces parallel to each other (side-by-side) on the same PCB layer. When traces must cross over each other do it at 90 degrees. Running digital and analog traces at 90 degrees to each other from the top to the bottom side as much as possible will minimize capacitive noise coupling and cross talk.

## **Revision History**

![](_page_28_Picture_31.jpeg)

![](_page_29_Figure_1.jpeg)

## **Notes**

**For more National Semiconductor product information and proven design tools, visit the following Web sites at:**

![](_page_30_Picture_306.jpeg)

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![](_page_30_Picture_12.jpeg)

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